

ABSTRACT

LASER PROCESSING METHOD

Disclosed herein is a laser processing method for processing a wafer held on a chuck table by applying a laser beam to the wafer. The laser processing method includes a forward path height storing step of positioning a height detecting unit in a work area of the wafer where the laser beam is to be applied, relatively moving the chuck table and the height detecting unit along a forward path in an X direction, detecting the height of the upper surface of the wafer along the forward path by using the height detecting unit, and storing height information detected by the height detecting unit at plural X coordinates on the forward path into a memory; and a backward path height storing step of relatively moving the chuck table and the height detecting unit along a backward path in the X direction, detecting the height of the upper surface of the wafer along the backward path by using the height detecting unit, and storing height information detected by the height detecting unit at plural X coordinates on the backward path into the memory.

(Figure 4A)